



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250602001.1

**Qualification of an alternate Mount Compound material for select devices
Change Notification / Sample Request**

Date: June 02, 2025

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250602001.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS61322DBZR	TPS61322DBZR
TMUX1219DCKR	TMUX1219DCKR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250602001.1			PCN Date:	June 02, 2025
Title:	Qualification of an alternate mount compound material for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	August 31, 2025		Sample Requests accepted until:	August 01, 2025*	
*Sample requests received after August 01, 2025 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
This PCN is to inform of an alternate Mount Compound material set for the list of devices in the product affected sections below.					
Group 1 Device:					
What		Current		Additional	
Mount Compound		SID#A-09		4229877	
Group 2 Device:					
What		Current		Additional	
Mount Compound		SID#A-09		4226215, 4229877	
Qualification results are shown below					
Reason for Change:					
Standardization					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS		REACH		Green Status	
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change	
IEC 62474					
<input checked="" type="checkbox"/> No Change					
Changes to product identification resulting from this PCN:					
None					
Group 1 Product Affected:					
TMUX1119DCKR		TMUX1219DCKR		TMUX1247DCKR	
Group 2 Product Affected:					
TPS61322DBZR		TPS61322DBZT			

Group 1 Qualification Report

Approve Date 01-May-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TMUX1119DCKR	Qual Device: TMUX1247DCKR	Qual Device: TMUX1219DCKR	QBS Reference: LM74700QDBVRQ1	QBS Reference: ESD2CANFD36DCKRQ1	QBS Reference: UCC287502DBVR	QBS Reference: ESD2CAN24DCKRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	2/154/0	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	-	2/154/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	1/77/0	1/77/0	3/231/0	1/77/0	3/231/0	2/154/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	1/30/0	1/30/0	1/30/0	3/30/0	1/30/0	-	1/30/0
FTY	E6	Final Test Yield	-	-	-	Pass	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device TMUX1119DCKR is qualified at MSL1 260C

Qual Device TMUX1247DCKR is qualified at MSL1 260C

Qual Device TMUX1219DCKR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-021

Group 2 Qualification Report

Approve Date 02-May-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC287502DBVR	QBS Reference: TPS3808EG01DBVRQ1	QBS Reference: LM74700QDBVRQ1	QBS Reference: PUCC287502DBVR
UHA	A3	Autoclave	121C/15psig	96 Hours	3/231/0	-	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	1/77/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	1/45/0	3/135/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	1/77/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	1/10/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/30/0	1/30/0	-

QBS: Qual By Similarity

Qual Device UCC287502DBVR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2312-020

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS

Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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